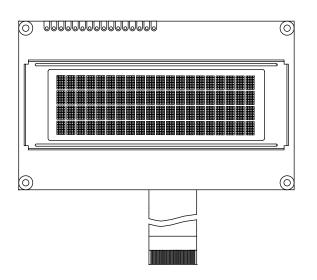


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RoHS

COMPLIANT

20 x 4 Character OLED



FEATURES

• Type: character

• Display format: 20 x 4 characters

• Built-in controller: OLED-0010

Duty cycle: 1/16+5 V power supplyInterface: 6800

Material categorization: for definitions of compliance

please see www.vishay.com/doc?99912

MECHANICAL DATA							
ITEM	ITEM STANDARD VALUE						
Module dimension	98.0 x 60.0 x 10.0 (max.)						
Viewing area	77.0 x 25.2						
Active area	70.16 x 20.95						
Dot size	0.54 x 0.55	mm					
Dot pitch	0.59 x 0.60	mm					
Mounting hole	93.0 x 55.0						
Character size	2.90 x 4.75						
Character pitch	3.54 x 5.40						

ABSOLUTE MAXIMUM RATINGS									
ITEM	CVMDOL	STANDAF	RD VALUE	LINUT					
ITEM	SYMBOL	MIN.	MAX.	UNIT					
Supply voltage for logic	V _{DD} to V _{SS}	-0.3	5.3	V					
Operating temperature	T _{OP}	-40	+80	°C					
Storage temperature	T _{STG}	-40	+80						

ELECTRICAL CHARACTERISTICS									
1774	SYMBOL CONDITION	CONDITION	ST	ANDARD VAL	.UE				
ITEM		CONDITION	MIN.	TYP.	MAX.	UNIT			
Supply voltage for logic	V _{DD} to V _{SS}	-	4.8	5.0	5.3				
Input high voltage	V _{IH}	-	0.8 V _{DD}	-	V_{DD}				
Input low voltage	V _{IL}	-	GND	-	0.2 V _{DD}	V			
Output high voltage	V _{OH}	I _{OH} = -0.5 mA	0.8 V _{DD}	=	V_{DD}]			
Output low voltage	V _{OL}	I _{OL} = 0.5 mA	GND	-	0.2 V _{DD}]			
50 % check board operating current	I _{DD}	V _{DD} = 5 V	50	57	65	mA			

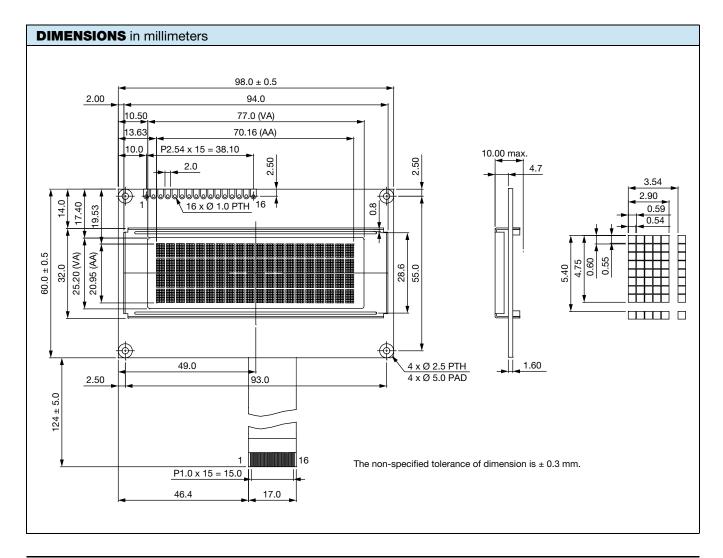
Note

• When you use 5 V for V_{DD}, please do not use 3 V or 3.3 V for logic I/O, this will cause module does not work.

OPTIONS									
EMITTING COLOR					MOQ				
YELLOW	GREEN	RED	BLUE	WHITE	YELLOW	GREEN	RED	BLUE	WHITE
_	-	-	Yes	-	-	-	-	Yes	-

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INTERFACE F	PIN FUNCTION	
PIN NO.	SYMBOL	FUNCTION
1	V _{SS}	Ground (0 V)
2	V _{DD}	Supply voltage for logic (5.0 V)
3	NC	No connection
4	RS	H / L, H: data; L: instruction code
5	R/W	H / L, H: read (module \rightarrow MPU); L: write (MPU \rightarrow module)
6	E	$H, H \rightarrow L$, chip enable signal
7	DB0	H / L, data bit 0
8	DB1	H / L, data bit 1
9	DB2	H / L, data bit 2
10	DB3	H / L, data bit 3
11	DB4	H / L, data bit 4
12	DB5	H / L, data bit 5
13	DB6	H / L, data bit 6
14	DB7	H / L, data bit 7
15	NC	No connection
16	NC	No connection





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1. Module Classification Information

1	Brand: Vishay Int	ertechnology, Inc.						
2	Horizontal Format: 20 Columns							
3	Display Type: N→0	Character Type, H→Graphic T	ype, Y→Tab Type, O→Cog					
4	Vertical Format: 4 I	_ines						
5	Serials code							
		A : Amber	R: RED					
6	Emitting Color	B: Blue	W: White					
		G: Green	L: Yellow					
7	Polarizer	P: With Polarizer; N: Withou	ut Polarizer					
8	Display Mode	P: Passive Matrix ; A: Active	e Matrix					
9	Driver Voltage	3: 3.0 V; 5: 5.0V						
10	Touch Panel	N: Without touch panel; T: \	With touch panel					
11	Products type	Standard type Sunlight Readable type Transparent OLED (TOLED) Flexible OLED OLED for Lighting						
12	Product grades	0 : Standard(A-level) 2 : B-level 3 : C-level 4 : high class(AA-level) 5 : Customer offerings						
13	Serial No.	Application serial number(00	JU~ZZZ)					



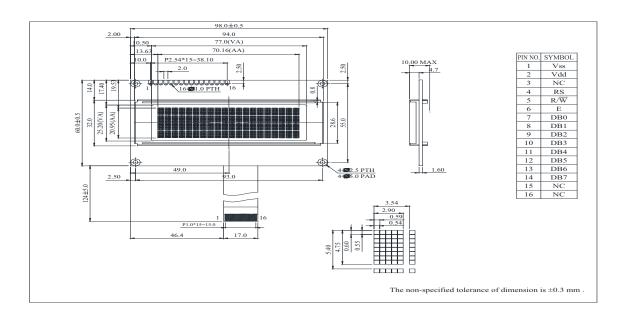
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2.General Specification

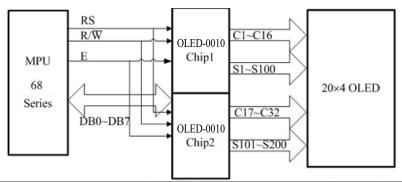
Item	Dimension	Unit
Number of Characters	20 characters x 4 Lines	_
Module dimension	98.0 x 60.0 x 10.0(MAX)	mm
View area	77.0 x 25.2	mm
Active area	70.16 x 20.95	mm
Dot size	0.54 x 0.55	mm
Dot pitch	0.59 x 0.60	mm
Character size	2.9 x 4.75	mm
Character pitch	3.54 x 5.4	mm
Panel type	OLED , Blue	1
Duty	1/16	

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3. Contour Drawing & Block Diagram







Address Fo	rmat		DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
CA (Character Address)			1	ADD6	ADD5	ADD4	ADD3	ADD2	ADD1	ADD0
Display position	1	2	3	4			17	18	19	20
DD RAM Address	00	01	02	03			10	11	12	13
DD RAM Address	40	41	42	43	·	mm	50	51	52	53
DD RAM Address	14	15	16	17			24	25	26	27
DD RAM Address	54	55	56	57	(*******	*****	64	65	66	67

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4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	VSS	0V	Ground
2	VDD	5.0V	Supply Voltage for logic
3	NC	_	
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read(Module→MPU) L: Write(MPU→Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bit 0
8	DB1	H/L	Data bit 1
9	DB2	H/L	Data bit 2
10	DB3	H/L	Data bit 3
11	DB4	H/L	Data bit 4
12	DB5	H/L	Data bit 5
13	DB6	H/L	Data bit 6
14	DB7	H/L	Data bit 7
15	NC	_	
16	NC	_	



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5.Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit	Notes
Operating Temperature	T _{OP}	-40	+80	$^{\circ}\!\mathbb{C}$	
Storage Temperature	T _{ST}	-40	+80	$^{\circ}\!\mathbb{C}$	
Supply Voltage For Logic	VDD-V _{SS}	-0.3	5.3	V	

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6.Electrical Characteristics

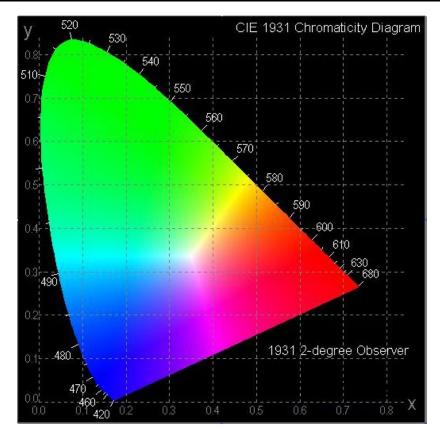
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	VDD-VSS	_	4.8	5.0	5.3	V
Input High Volt.	VIH	_	0.8 VDD	_	VDD	V
Input Low Volt.	VIL	_	GND	_	0.2 VDD	V
Output High Volt.	VOH	IOH=-0.5mA	0.8 VDD	_	VDD	V
Output Low Volt.	VOL	IOL=0.5mA	GND	_	0.2 VDD	V
50% Check Board Operating Current	IDD	VDD=5V	50	57	65	mA

Note: When you use 5V for Vdd please don't use 3V or 3.3V for logic I/O this will cause module does not work.

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7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	(V)θ		160			deg
View Angle	(Η)φ		160			deg
Contrast Ratio	CR	Dark	2000:1		_	_
Deenene Time	T rise	_		10		μs
Response Time	T fall	_		10		μs
Display with 50% check	Board Brightne	ess	50	60		cd/m2
CIEx(Blue)		(CIE1931)	0.12	0.16	0.20	
CIEy(Blue)		(CIE1931)	0.19	0.23	0.27	





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8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	40,000 Hrs	50,000 Hrs	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.

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9.Reliability

Content of Reliability Test

Environmenta	al Test	T	Ammlicable
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80 °C 240hrs	
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80 °C 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40 °C 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90% RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40 °C 25°C 30min 5min 30min 1 cycle	-40 °C/80°C 100 cycles	
Mechanical Te	st		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	
Others			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS= ± 600 V(contact) ± 800 v(air), RS= 330Ω CS= 150 pF 10 times),

^{**} Supply voltage for OLED system =Operating voltage at 25°C

OLED-020N004B-BPP5N00000



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Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.

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10.Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 		0.65		
02	Black or white spots on OLED (display only)	 2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm. 		2.5		
03	OLED black spots, white spots, contamina tion (non-displ ay)	3.1 Round type : As following drawing Φ=(x+y)/2		SIZE $\Phi \le 0.10$ $0.10 < \\ \Phi \le 0.20$ $0.20 < \\ \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2	2.5
		3.2 Line type : (As foll Length Lengt	3.0 2.5	drawing) Width W ≤ 0.02 0.02 < W ≤ 0.03 0.03 < W ≤ 0.05 0.05 < W	Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spo specifications, not east of find, must check in specify direction.	t	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5



NO	Item	Criterion	AQL	
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination		
			1	
06	Chipped glass		2.5	
		6.1.2 Corner crack:		
		$ \begin{array}{ c c c c c c }\hline z: Chip thickness & y: Chip width & x: Chip length\\\hline Z \leq 1/2t & Not over viewing & x \leq 1/8a\\ & area & \end{array} $		
		1/2t < z ≤ 2t Not exceed 1/3k x ≤ 1/8a		
		⊙ If there are 2 or more chips, x is the total length of each of	chip.	



Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad: y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t y: Chip width x: Chip length z: Chip thickness y≤L x≤1/8a 0 < z≤t off the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. off the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length y≤1/3L x≤a	NO	Item	Criterion	AQL			
x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad: y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t 6.2.2 Non-conductive portion: Glass crack y: Chip width x: Chip length z: Chip thickness y≤L x≤1/8a 0 < z≤t Off the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Off the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length x: len	110	10111		nqL			
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal:				
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			Z Chin shidh and a Chin shidh and				
Glass crack Y							
Glass crack y: Chip width x: Chip length z: Chip thickness y \leq L x \leq 1/8a 0 < z \leq t							
ob crack y: Chip width x: Chip length y≤ L y≤ L x≤1/8a o < z ≤ t olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x y: width x x y: width x: Chip thickness y≤ t olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.			o.2.2 Non conadoure person.				
ob crack y: Chip width x: Chip length y≤ L y≤ L x≤1/8a o < z ≤ t olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x y: width x x y: width x: Chip thickness y≤ t olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.							
ob crack y: Chip width x: Chip length y≤ L y≤ L x≤1/8a o < z ≤ t olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x y: width x x y: width x: Chip thickness y≤ t olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.		۵.					
y: Chip width x: Chip length z: Chip thickness y ≤ L x ≤ 1/8a 0 < z ≤ t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length	06						
thickness y ≤ L olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length		Crack y					
thickness y ≤ L olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length			X				
y ≤ L x ≤ 1/8a 0 < z ≤ t ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length							
must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length							
specifications. If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length			⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO				
 ○ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length 							
mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length			· ·				
6.2.3 Substrate protuberance and internal crack. y: width x: length							
y: width x: length							
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NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65





	NO	Item	Criterion	AQL
interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins.		General	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to 	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Fixed C Light Fixed

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11.Precautions in use of OLED Modules

Modules

- (1)Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3)Don't disassemble the OLED display module.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist OLED display module.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8)It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9)Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) Vishay has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Vishay have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Vishay have the right to modify the version.)

11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent
 - Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent

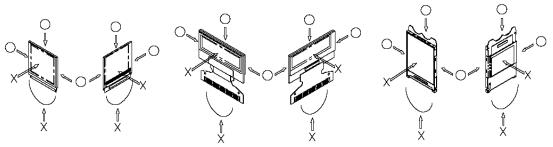
such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts.
 - These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



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- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

11.2. Storage Precautions

(1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. and, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.

(We recommend you to store these modules in the packaged state when they were shipped from Vishay.

At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.

(2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.

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- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.
- * Connection (contact) to any other potential than the above may lead to rupture of the IC.

11.4. Precautions when disposing of the OLED display modules

 Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

11.5. Other Precautions

- (1) When an OLED display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur.
- Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module.
- (2) To protect OLED display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OLED display modules.
- * Pins and electrodes
- * Pattern layouts such as the TCP & FPC
- (3) With this OLED display module, the OLED driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OLED driver is exposed to light, malfunctioning may occur.
- * Design the product and installation method so that the OLED driver may be shielded from light in actual usage.
- * Design the product and installation method so that the OLED driver may be shielded from light during the inspection processes.
- (4) Although this OLED display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.
- (5) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (6)Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.
- (7)Our company will has the right to upgrade and modify the product function.

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